ASMPT Brings Proven TCB Solutions to the Market

We are pleased to announce that ASM Pacific Technology (ASMPT) and our leading TCB customer (the world's leading integrated IDM) will co-present a white paper in SEMICON Taiwan's Advanced Packaging symposium on Sept 3, 2014 titled: **"Thermo-Compression Bonding (TCB) for fine-pitch copper pillar flip chip interconnect"**

This white paper will introduce a proven high quality flux TCB process used in high precision, high volume manufacturing of large die on advanced wafer nodes. This paper will also introduce proven portable module solutions / core technologies to address challenges of TCB process.

The white paper demonstrates our customer's advanced interconnect process and application know-how. It also showcases ASMPT's automation competency and her ability to bring TCB solutions to the broader market

SW Lau, General Product Manager of ASMPT (TCB applications), remarked, *"Working with our leading customer in TCB bonding to deliver high quality bonds on advanced wafer nodes has been a significant milestone in our advanced application roadmap. The strategic value to our customer is to drive down the cost of ownership continuously, by enabling wider adoption on a future proof platform that is forward compatible with ever reducing wafer nodes applications."*

To attend the Advanced Packaging Symposium at SEMICON Taiwan for this session

Date: September 03, 2014 Wednesday
Time: 14:20 – 14:45
Registration: 08:30 - 09:00
Venue: Room 504, 5F, TWTC Nangang Exhibition Hall, Taipei

Visit ASMPT **booth# 873** at SEMICON Taiwan 2014 to learn more.

Contacts for enquiries:

Name:	**Nelson Fan**	**Ringo Tse**
Title:	**Business Development Manager**	**Product Marketing Manager**
Email:	**chfan@asmpt.com**	**ringo.tse@asmpt.com**
Direct line:	**(852) 2619 - 5208**	**(852) 2619 - 2250**